Manufacturer: DNS SK-200V-AVPE
Coater/Developer Track

Wafer Size: 8
Vintage: 1999,12

1. Spin coater(SC)
1) Spin motor

Rotation speed: 0 – 6000 rpm (CW,CCW)
Max acceleration: 30000 rpm/s
Rotation accuracy: ±1.5 rpm
Flange cooling: Temperature control by circulating water

2) Spin chuck
Material: PEEK

3) Resist nozzle
Scan speed: 25 – 85 mm/s
Resist temperature control:
Circulating water control with triple pipe structure
Line: Max 6 line(3 line – 1 temperature control)

4) Pot rinse
Rinse dispense flow: Max 30 mL/min

5) Edge cleaner nozzle
Rinse dispense position: 0-10mm from edge
Minimum set: 0.1mm

6) Back rinse
Rinse dispense line: 2 line
Rinse dispense flow: 50 mL/min

7) Cup
Top cup material: PP
Middle cup material: PP
Bottom cup material: PPS

8) Cup rinse
Rinse dispense flow: Max 500 mL/min

9) Exhaust
Exhaust box material: SUS304
Dumper: Cylinder open-close control

10) Resist dummy dispense: Auto or Pre-dispense

2. Spin coater(SC)/ T-ARC
1) Spin motor

Rotation speed: 0 – 6000 rpm (CW,CCW)
Max acceleration: 30000 rpm/s
Rotation accuracy: ±1.5 rpm
Flange cooling: Temperature control by circulating water

2) Spin chuck
Materials: PEEK

3) T-ARC nozzle
Scan speed: 25 – 85 mm/s
Resist temperature control:
Circulating water control with triple pipe structure
Line: Max 4 line

4) Pot rinse
Rinse dispense flow: Max 30 mL/min

5) Edge cleaner nozzle
Rinse dispense position: 0-10mm from edge
Minimum set: 0.1mm

6) Back rinse
Rinse dispense line: 2 line
Rinse dispense flow: 50 mL/min

7) Cup
Top cup material: PP
Middle cup material: PP
Bottom cup material: PPS

8) Exhaust
Exhaust box material: SUS304
Dumper: Cylinder open-close control

9) T-ARC dummy dispense: Auto or Pre-dispense

3. Spin developer

1) Spin motor
Rotation speed: 0 – 6000 rpm (CW,CCW)
Max acceleration: 30000 rpm/s
Rotation accuracy: ±1.5 rpm

2) Spin chuck
Material: PEEK

3) Nozzle
Scan speed: 25 – 100 mm/s
Line: Max 2 line (Same temperature control)

4) Nozzle cleaning
Nozzle cleaning dispense flow: Max 1 L/min
N2 Nozzle blow: Nozzle side
Drip removal: Ejector vacuum

5) Pure water rinse

Rinse dispense flow: Max 2 L/min
Line: 2 line

6) Back rinse
Rinse dispense output: 4 line

7) Cup
Cup material: PP
Splash guard material: PP
Inner cup material: PP

8)Exhaust
Exhaust Box material: SUS304
Exhaust dumper: Cylinder Open-close control

9) Drain
Liquid-Vapor Separation: Processed by Box under the Cup

10) Liquid dummy dispense: Auto or Pre dispense

3. Spin developer

1) Spin motor
Rotation speed: 0 – 6000 rpm (CW,CCW)
Max acceleration: 30000 rpm/s
Rotation accuracy: ±1.5 rpm

2) Spin chuck
Material: PEEK

3) Nozzle
Scan speed: 25 – 100 mm/s
Line: Max 2 line (Same temperature control)

4) Nozzle cleaning
Nozzle cleaning dispense flow: Max 1 L/min
N2 Nozzle blow: Nozzle side
Drip removal: Ejector vacuum

5) Pure water rinse
Rinse dispense flow: Max 2 L/min
Line: 2 line

6) Back rinse
Rinse dispense output: 4 line

7) Cup
Cup material: PP
Splash guard material: PP
Inner cup material: PP

8)Exhaust
Exhaust Box material: SUS304
Exhaust dumper: Cylinder Open-close control

9) Drain

Liquid-Vapor Separation: Processed by Box under the Cup

10) Liquid dummy dispense: Auto or Pre dispense

4. Deep UV wafer edge exposure unit (EE)

1) Wafer detect: Vacuum sensor

2) Edge detect: Image sensor detect

3) Source: 200W HG – Xe lamp

4) Illumination limit control: Feedback auto-control

5)Filter select: Max 6 sheet, Auto-change

(248 band pass filter: 1 sheet standard)

(ND filter, Wave select filter, etc.)

5. Indexer

1) Built-in SMIF

* ASYST INX2200

* Wafer detect

* Cassette detect

* POD detect